

Full Material Declaration

物質宣告表

Manufacture name	LCD Module			Issue Date (yyyy/mm/dd)	2025/6/27		
Model name	G121ICE-L01			Product weight (g)	475 g		
Part Name	Part mass (g)	Homogeneous Material name	Material mass (g)	Substance name	CAS No.	weigh% of substance	Remark
Glass	195.5043	Glass	195.5043	Fiber Glass Wool	65997-17-3	100.00%	
PF-CF	5.6401	Adhesive	1.01	Acrylic adhesive	-	100.00%	
PF-CF		Ink	0.0001	2-Butanone;Ethyl methyl ketone	78-93-3	70.00%	
				Ethanol	64-17-5	5.00%	
				Isopropanol;2-Propanol	67-63-0	2.00%	
				Ethyl acetate;Acetic acid ethyl ester	141-78-6	2.00%	
				Other substance	Other substance	21.00%	
PF-CF		PVA	1.99	Ethenol, homopolymer, ester with boric acid;	55199-96-7	96.05%	
				Boric acid	10043-35-3	0.25%	
				Iodine;	7553-56-2	3.70%	
PF-CF		TAC	2.64	triacetate cellulose film bas	9012-09-3	88.460200%	
				Dichloromethane	75-09-2	0.04%	
				Acrylic urethane hard coat resin	-	11.50%	
PF-TFT	5.4701	Adhesive	0.98	Acrylic adhesive	-	100.00%	
PF-TFT		Ink	0.0001	Acetone;2-Propanone	67-64-1	35.00%	
				Ethanol	64-17-5	35.00%	
				Isopropanol;2-Propanol	67-63-0	3.50%	
				Propyl acetate	109-60-4	2.00%	
				Other substance	Other substance	24.50%	
PF-TFT		PVA	1.93	Ethenol, homopolymer, ester with boric acid;	55199-96-7	96.05%	
				Boric acid	10043-35-3	0.25%	
				Iodine;	7553-56-2	3.70%	
PF-TFT		TAC	2.56	triacetate cellulose film bas	9012-09-3	89.250000%	
				Dichloromethane	75-09-2	0.04%	
				Acrylic urethane hard coat resin	-	10.71%	
LN	12.3	BEF	12.3	9,9-Bis[4-(2-acryloyloxyethoxy)phenyl]fluorene;	161182-73-6	10.00%	
				Poly(ethylene terephthalate);PET	25038-59-9	90.00%	
LH	12.4	BEF	12.4	Poly(ethylene terephthalate);PET	25038-59-9	90.00%	
				EBECRYL 600;	71281-65-7	10.00%	
DD	12.9	DD	12.9	Poly(ethylene terephthalate);PET	25038-59-9	91.98%	
				2-Propenoic acid,2-methyl-, methyl ester, homopolymer	9011-14-7	4.00%	
				Acrylic resin,water-soluble;	25767-39-9	4.00%	
				Antimony	7440-36-0	0.02%	
DU	12.9	DU	12.9	Poly(ethylene terephthalate);PET	25038-59-9	65.98%	
				2-Propenoic acid,2-methyl-, methyl ester, homopolymer	9011-14-7	17.00%	
				Polyacrylic acid; 2-Propenoic acid homopolymer	9003-01-4	17.00%	
				Antimony	7440-36-0	0.02%	
RN	7.6	RN	7.6	Poly(ethylene terephthalate);PET	25038-59-9	53.00%	
				Titanium dioxide;	13463-67-7	16.00%	
				PolystPolyster resin	-	23.00%	
				Polyolefin resin	-	8.00%	
IC,G-COG	0.009	Bump	0.0003	Titanium	7440-32-6	0.09%	
				Tungsten;	7440-33-7	1.75%	
				Gold	7440-57-5	98.16%	
IC,G-COG		Die	0.0087	Aluminium;	7429-90-5	0.15%	
				Silicon;	7440-21-3	99.64%	
				Titanium	7440-32-6	0.10%	
				Tungsten;	7440-33-7	0.10%	
				Arsenic	7440-38-2	0.0001%	
				Boron;	7440-42-8	0.0030%	
				Copper (metallic)	7440-50-8	0.0020%	
				Other Element Phosphorus	INX-066	0.0030%	
IC,S-COF	0.1212	Base	0.0562	[5,5'-Bisobenzofuran]-1,1',3,3'-tetrone, polymer with 1,4-benzenediamine;poly(biphenyltetracarboxylic dianhydride-co-pheny	29319-22-0	99.30%	
				Silicon dioxide	7631-86-9	0.70%	
IC,S-COF		Bump	0.0001	Titanium	7440-32-6	0.09%	
				Tungsten;	7440-33-7	1.75%	
				Gold	7440-57-5	98.16%	
IC,S-COF		Copper_Pattern	0.0391	Copper (metallic)	7440-50-8	100.000000%	
IC,S-COF		Die	0.0105	Aluminium;	7429-90-5	0.200000%	
				Silicon;	7440-21-3	99.71%	
				Titanium	7440-32-6	0.06%	
				Tungsten;	7440-33-7	0.04%	
				Antimony	7440-36-0	0.0002%	
				Arsenic	7440-38-2	0.0002%	
				Boron;	7440-42-8	0.0001%	
				Copper (metallic)	7440-50-8	0.0010%	
				Other Element Phosphorus	INX-066	0.0001%	

IC,S-COF		Plating	0.0017	Tin(II) Alkylsulfonate	---	15.00%	
				Alkylsulfonic acid	--	30.00%	
				Water;dihydrogen oxide	7732-18-5	38.00%	
				Phenol	108-95-2	1.00%	
				Thiourea;Thiocarbamide	62-56-6	15.00%	
				Arsenic and its compounds	-	1.00%	
IC,S-COF		Resin	0.0035	Additives(trade secret)	-	4.00%	
				Acid anhydride type hardener酸酐型固化剂	--	60.000000%	
				N,N-DIGLYCIDYL-4-GLYCIDYLOXYANILINE;4-(2-Oxiranylmethoxy)-N,N-bis(2-oxiranylmethyl)aniline	5026-74-4	20.000000%	
				Solvent black 7;C.I. 50415:1	8005-02-5	1.000000%	
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	15.000000%	
IC,S-COF		SR	0.0101	Pigment(trade secret)	-	1.00%	
				Layered double hydroxide	--	9.000000%	
				Polyimide resin modified polyurethane	---	85.00%	
				4,4'-Methylenebis(N,N-diglycidylaniline);4,4'-Methylenebis[N,N-bis(2,3-epoxypropyl)aniline]	28768-32-3	5.000000%	
IC,Tcon	0.176	Wire Copper	0.0005	Palladium;E 1010/W	7440-05-3	3.100000%	
				Copper (metallic)	7440-50-8	96.550000%	
				Gold	7440-57-5	0.350000%	
IC,Tcon		Die	0.0015	Aluminium;	7429-90-5	0.206630%	
				Nickel	7440-02-0	0.004710%	
				Silicon;	7440-21-3	99.05%	
				Tantalum;tantalum, metal	7440-25-7	0.108920%	
				Titanium	7440-32-6	0.0012500%	
				Tungsten;	7440-33-7	0.01%	
				Arsenic	7440-38-2	0.0003%	
				Boron;	7440-42-8	0.00004%	
				Copper (metallic)	7440-50-8	0.60%	
				Germanium;Germaniumelement	7440-56-4	0.02%	
				Phosphorus	7723-14-0	0.0002%	
				Fluorine	7782-41-4	0.0002%	
IC,Tcon		Die_Attach	0.0003	Hardener	-	5.000000%	
				Epoxy resin	-	6.00%	
				1,4-Bis((2,3-epoxypropoxy)methyl)cyclohexane;Cyclohexane, 1,4-bis[(2,3-epoxypropoxy)methyl]- (8CI)	14228-73-0	4.00%	
				1,1-Di(tert-butylperoxy)cyclohexane;Cyclohexylidenebis(tert-butyl)peroxide	3006-86-8	1.00%	
				Dicyanodiamide;1-Cyanoguanidine	461-58-5	0.50%	
				Silver;	7440-22-4	73.500000%	
				Phenolic epoxy resin F-44; Formaldehyde, polymer with (chloromethyl) oxirane and phenol	9003-36-5	4.000000%	
				Ethylene dimethacrylate;1,2-Ethanediol dimethacrylate	97-90-5	6.000000%	
IC,Tcon		Molding_Compound	0.0964	Epoxy Resin A(Trade Secret)	-	3.000000%	
				Phenol Resin(Trade Secret)	-	7.500000%	
				Carbon Black	1333-86-4	0.550000%	
				Silicon dioxide;Silica	60676-86-0	78.450000%	
				Silicon dioxide	7631-86-9	7.500000%	
IC,Tcon		Wire Gold	0.0002	Palladium;E 1010/W	7440-05-3	0.950000%	
				Beryllium	7440-41-7	0.000500%	
				Gold	7440-57-5	99.047500%	
				Calcium;	7440-70-2	0.002000%	
IC,Tcon		Lead_Frame	0.0025	Silver;	7440-22-4	100.00%	
IC,Tcon		Lead_Frame	0.0695	Magnesium	7439-95-4	0.35%	
				Nickel	7440-02-0	1.16%	
				Silicon;	7440-21-3	3.09%	
				Silver;	7440-22-4	3.50%	
				Copper (metallic)	7440-50-8	91.90%	
IC,Tcon		Solder	0.0051	Tin	7440-31-5	100.00%	
IC	0.043	Die	0.001	Silicon;	7440-21-3	99.79%	
				Aluminium;	7429-90-5	0.13%	
				Tungsten;	7440-33-7	0.04%	
				Titanium	7440-32-6	0.03%	
				Copper (metallic)	7440-50-8	0.0014%	
				Boron;	7440-42-8	0.0013%	
				Cobalt	7440-48-4	0.0013%	
IC		Die_Attach	0.001	Arcylate	/	30.00%	
				Curing agent & hardener	Proprietary	10.00%	
				Silver;	7440-22-4	60.00%	
IC		Lead_Frame	0.0068	Copper (metallic)	7440-50-8	97.27%	
				Iron;	7439-89-6	2.50%	
				Lead;	7439-92-1	0.01%	
				Other Element Phosphorus	INX-066	0.03%	
				Zinc	7440-66-6	0.20%	

IC		Molding_Compound	0.032	Epoxy Resin 1	Trade secret	3.00%	
				Epoxy Resin 2	Trade secret1	1.00%	
				Phenolic resin	Trade secret2	4.00%	
				Other Element Phosphorus	INX-066	0.300000%	
				Carbon Black	1333-86-4	0.200000%	
				Silicon dioxide;Silica	60676-86-0	80.000000%	
				Silicon dioxide	7631-86-9	11.500000%	
IC		Plating	0.0015	Tin	7440-31-5	100.000000%	
IC		Wire	0.0007	Copper (metallic)	7440-50-8	96.90%	
				Iron;	7439-89-6	0.0005%	
				Aluminium;	7429-90-5	0.0005%	
				Palladium;E 1010/W	7440-05-3	3.10%	
				Silver;	7440-22-4	0.001500%	
PWM	0.0419	Die	0.0021	Aluminium;	7429-90-5	0.60%	
				Silicon;	7440-21-3	99.40%	
PWM		Die_Attach	0.0001	Silver;	7440-22-4	82.000000%	
				Acrylate		4.00%	
				Acrylic resin		8.00%	
				Additive		1.00%	
				Butadiene copolymer		1.00%	
				Epoxy Resin		1.00%	
				Polybutadiene derivative		2.50%	
				Peroxide		0.50%	
PWM		Lead_Frame	0.02	Copper (metallic)	7440-50-8	97.22%	
				Iron;	7439-89-6	2.29%	
				Zinc	7440-66-6	0.15%	
				Other Element Phosphorus	INX-066	0.03%	
				Silver;	7440-22-4	0.31%	
PWM		Molding_Compound	0.0175	Carbon Black	1333-86-4	0.10%	
				Silicon dioxide;Silica	60676-86-0	79.00%	
				Silicon dioxide	7631-86-9	5.00%	
				Epoxy Resin 1	Trade Secret	5.00%	
				Epoxy Resin 2	-	5.00%	
				Organophosphorus compounds	-	0.90%	
				Phenolic Resin	-	5.00%	
PWM		Plating	0.0021	Tin	7440-31-5	100.00%	
PWM		Wire	0.0001	Copper (metallic)	7440-50-8	98.800000%	
				Palladium;E 1010/W	7440-05-3	1.200000%	
MOS	0.0058	Die	0.0001	Silicon;	7440-21-3	90.930000%	
				Gold	7440-57-5	9.070000%	
MOS		Lead_Frame	0.0019	Iron;	7439-89-6	58.000000%	
				Nickel	7440-02-0	42.00%	
MOS		Molding_Compound	0.0031	Silicon dioxide;Silica	60676-86-0	58.97%	
				Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	14.36%	
				Phenolic Resin	9003-35-4	7.69%	
				Aluminium hydroxide	21645-51-2	17.950000%	
				Brominated flame retardant which comes under notation of ISO 1043-4 code number FR(42)[Brominated organic phosphorus compounds]	-	0.51%	
				Carbon Black	1333-86-4	0.51%	
MOS		Plating_Copper	0.0003	Copper (metallic)	7440-50-8	100.00%	
MOS		Plating_Tin	0.0003	Tin	7440-31-5	98.00%	
				Copper (metallic)	7440-50-8	2.00%	
				Lead;	7439-92-1	0.0001%	
MOS		Wire	0.0001	Gold	7440-57-5	100.00%	
Diode	0.0188	Die	0.0011	Nickel	7440-02-0	0.15%	
				Silicon;	7440-21-3	99.21%	
				Arsenic	7440-38-2	0.09%	
				Gold	7440-57-5	0.55%	
Diode		High_Temp_Solder_Paste	0.0016	Lead;	7439-92-1	92.50%	
				Silver;	7440-22-4	2.50%	
				Tin	7440-31-5	5.00%	
Diode		Lead_Frame-1	0.0088	Copper (metallic)	7440-50-8	97.00%	
				Iron;	7439-89-6	3.00%	
Diode		Lead_Frame-2	0.0021	Copper (metallic)	7440-50-8	97.60%	
				Iron;	7439-89-6	2.40%	
Diode		Molding_Compound	0.0051	Silicon dioxide;Silica	60676-86-0	79.70%	
				Poly[(o-cresyl glycidyl ether)-co-formaldehyde]	29690-82-2	10.00%	
				Phenolic Resin	9003-35-4	10.00%	
				Carbon Black	1333-86-4	0.30%	
Diode		Plating	0.0001	Tin	7440-31-5	99.99%	
				Lead;	7439-92-1	0.01%	
PCB_OE	19.6	Copper_Foil	11.66	Arsenic	7440-38-2	0.0040%	
				Chromium	7440-47-3	0.0030%	
				Copper (metallic)	7440-50-8	99.90%	
				Nickel	7440-02-0	0.0030%	
				Zinc	7440-66-6	0.09%	
PCB_OE		Copper_Plating	0.258	Copper (metallic)	7440-50-8	99.90%	
				Benzoicacid, 2-amino-5-(4,4,5,5-tetramethyl-1,3,2-dioxaborolan-2-yl)-, methyl ester	无	0.10%	
PCB_OE		Gold_Plating-1	0.007	Potassium dicyanoaurate;Aurate(1-),bis(cyano-C)-, potassium	13967-50-5	100.00%	

PCB_OE		Gold_Plating-2	0.007	Ammonium citrate dibasic; Diammonium hydrogen citrate	3012-65-5	45.00%	
				Water; dihydrogen oxide	7732-18-5	55.00%	
PCB_OE		Ink	0.465	Acrylate modified epoxy resin	168750-21-8	54.00%	
				Titanium dioxide;	13463-67-7	16.00%	
				Talc	14807-96-6	16.00%	
				Trimethylolpropane triacrylate; TMPTA	15625-89-5	12.00%	
				Silicon dioxide	7631-86-9	2.00%	
PCB_OE		Nickel_Plating	0.337	Nickel sulphate	7786-81-4	25.00%	
				Water; dihydrogen oxide	7732-18-5	75.00%	
PCB_OE		Prepreg	6.565	Fiber Glass Wool	65997-17-3	30.00%	
				Silicon dioxide; Silica	60676-86-0	20.00%	
				Phenolic Resin	9003-35-4	23.00%	
				Phenol polymer with formaldehyde glycidyl ether	28064-14-4	27.00%	
PCB_OE		Solder_Resist_Ink	0.301	Solvent naphtha	64742-94-5	7.00%	
				2-(2-Ethoxyethoxy)ethyl acetate	112-15-2	11.00%	
				2-Methyl-4-(methylthio)-2-morpholinopropiophenone; 2-Methyl-1-[4-(methylthio)phenyl]-2-(4-morpholinyl)-1-propanone	71868-10-5	2.00%	
				Dipentaerythritol hexaacrylate; 2-[[[3-[(1-oxoallyl)oxy]-2,2-bis[[[(1-oxoallyl)oxy]methyl]propoxy]methyl]-2-[[[(1-oxoallyl)oxy]methyl]-1,3-propanediyl diacrylate	29570-58-9	1.00%	
				Dipentaerythritol pentaacrylate; 2-Propenoic acid, 2-[[3-hydroxy-2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]propoxy]methyl]-2-[[[(1-oxo-2-propenyl)oxy]methyl]-1,3-propanediylester (9CI)	60506-81-2	1.00%	
				Naphthalene	91-20-3	0.0001%	
				1L,3,5-tris(oxiranylmethyl)-1L,3,5-triazine-2,4,6(1H,3H,5H)-trione; TGIC	2451-62-9	7.00%	
				Poly(Bisphenol A-co-epichlorohydrin) glycidyl end-capped	25036-25-3	4.00%	
				Formaldehyde, polymer with (chloromethyl)oxirane and 4,4- (1-methylethylidene)bis[phenol];	28906-96-9	7.00%	
				Melamine	108-78-1	7.00%	
				Phenol polymer with formaldehyde glycidyl ether	28064-14-4	4.00%	
				4,4-propane-2,2-diyl diphenol - 2-(chloromethyl)oxirane (1:1)	25068-38-6	4.00%	
				Barium sulfate; BaSO4	7727-43-7	13.40%	
				Silica, Crystalline	14808-60-7	13.40%	
				Talc	14807-96-6	18.20%	
Res-SMD	0.00233	Conductor_Layer	0.0001	Silver;	7440-22-4	67.90%	
				Terpineol; 2-(4-Methyl-3-cyclohexenyl)-2-propanol	8000-41-7	9.00%	
				Palladium; E 1010/W	7440-05-3	0.90%	
				Fiber Glass Wool	65997-17-3	13.20%	
				Stoddard solvent; Low boiling point naphtha - unspecified	8052-41-3	9.00%	
Res-SMD		End_Terminal	0.0001	Nickel	7440-02-0	80.00%	
				Chromium	7440-47-3	20.00%	
Res-SMD		Ink	0.0001	Bisphenol A epoxy resin E-03; 2,2-[[[1-methylethylidene)bis(4,1-phenyleneoxy)methylene]]bis-oxiran homopolymer	25085-99-8	50.00%	
				Barium sulfate; BaSO4	7727-43-7	15.00%	
				Titanium dioxide;	13463-67-7	30.00%	
				Naphtha; Low boiling point naphtha	8030-30-6	5.00%	
Res-SMD		Over_Coating	0.00003	4,4-propane-2,2-diyl diphenol - 2-(chloromethyl)oxirane (1:1)	25068-38-6	50.00%	
				Silicon dioxide; Silica	60676-86-0	35.00%	
				Talc	14807-96-6	15.00%	
Res-SMD		Plating Nickel	0.0001	Nickel	7440-02-0	100.00%	
Res-SMD		Plating Tin	0.0001	Tin	7440-31-5	100.00%	
Res-SMD		Resistive_Layer	0.0001	Silver;	7440-22-4	40.00%	
				Palladium; E 1010/W	7440-05-3	15.00%	
				Ruthenium dioxide	12036-10-1	25.00%	
				Frits, chemicals; Bleihaltige Fritten, Chemikalien	65997-18-4	20.00%	
Res-SMD		SUBSTRATE	0.0017	Aluminum oxide;	1344-28-1	96.00%	
				Silica, Crystalline	14808-60-7	3.00%	
				Magnesium oxide	1309-48-4	1.00%	
ESD-P	0.0049	Outer_Electrode	0.0001	Polyether Resins	-	10.00%	
				2-butoxyethoxy ethanol (DEGBE)	112-34-5	10.00%	

				3-Glycidoxypolytrimethoxysilane;[3-(2,3-Epoxypropoxy)propyl]trimethoxysilane	2530-83-8	10.00%	
				Methoxypropoxypropanol	34590-94-8	10.00%	
				Silver;	7440-22-4	60.00%	
ESD-P		Plating Nickel	0.0001	Nickel	7440-02-0	100.00%	
ESD-P		Plating Other Metal	0.0001	Tin	7440-31-5	100.00%	
ESD-P		Inner_Electrode-1	0.0001	Benzyl alcohol;alpha-Hydroxytoluene	100-51-6	5.00%	
				2-Butoxyethanol	111-76-2	5.00%	
				Fiber Glass Wool	65997-17-3	5.00%	
				Silver;	7440-22-4	70.00%	
				Terpineol;2-(4-Methyl-3-cyclohexenyl)-2-propanol	8000-41-7	5.00%	
				Resin acids and Rosin acids, esters with pentaerythritol;PENTAERYTHRITYL ROSINATE	8050-26-8	5.00%	
				Ethyl cellulose	9004-57-3	5.00%	
ESD-P		Inner_Electrode-2	0.0001	p-menthan-8-ol;1-methyl-4-isopropylcyclohexane-8-ol	498-81-7	30.00%	
				Normal alkane;Normal paraffins	64771-72-8	10.00%	
				Palladium;E 1010/W	7440-05-3	55.00%	
				Ethyl cellulose	9004-57-3	5.00%	
ESD-P		Ceramic_Chip Chemical	0.0039	Zinc oxide; Zinc white; C.I. pigment white 4	1314-13-2	100.00%	
ESD-P		Ceramic_Chip Metal	0.0004	Praseodymium oxide;Praseodymium(III,IV) oxide	12037-29-5	3.52%	
				Cobalt oxide (Co3O4)	1308-06-1	2.77%	
				Neodymium oxide;Dineodymium trioxide	1313-97-9	1.89%	
				Zinc oxide; Zinc white; C.I. pigment white 4	1314-13-2	91.82%	
ESD-P		Ink	0.0001	Epoxy resin/182697-62-7	-	60.00%	
				Carbon Black	1333-86-4	15.00%	
				Talc	14807-96-6	10.00%	
				Solvent naphtha	64742-94-5	15.00%	
MLCC	0.0016	Ceramic_Element	0.0011	Barium titanate	12047-27-7	100.00%	
MLCC		Inner_Electrode	0.0001	Nickel	7440-02-0	100.00%	
MLCC		Outer_Electrode	0.0002	Copper (metallic)	7440-50-8	100.00%	
MLCC		Plating Nickel	0.0001	Nickel	7440-02-0	100.00%	
MLCC		Plating Tin	0.0001	Tin	7440-31-5	100.00%	
IND	1.4228	Inner_Coil(Copper)	0.2231	Copper (metallic)	7440-50-8	100.00%	
IND		Inner_Coil(Polyamideimide_Resin)	0.0142	Polyurethane; TPU	9009-54-5	100.00%	
IND		Marking	0.0001	2-Butanone;Ethyl methyl ketone	78-93-3	95.00%	
				ChromeIII-Complex Dye	NA	5.00%	
IND		Outer_Molding	1.0724	Iron;	7439-89-6	97.00%	
				Carbon;Activated carbon	7440-44-0	1.00%	
				Nitrogen	7723-37-9	1.00%	
				Oxygen;Dioxygen	7782-44-7	1.00%	
IND		Terminal_Plating	0.113	Copper (metallic)	7440-50-8	99.80%	
				Nickel	7440-02-0	0.02%	
				Tin	7440-31-5	0.18%	
Conn	0.053	Housing Other Plastic	0.021	Other	-	1.00%	
				1,4-Benzenedicarboxylic acid polymer with [1,1'-biphenyl]-4,4'-diol, 4-hydroxy benzoic acid, 6-hydro	147310-94-9	59.00%	
				Talc	14807-96-6	20.00%	
				Fiber Glass Wool	65997-17-3	20.00%	
Conn		Housing Pa6	0.013	1,4-Benzenedicarboxylic acid,polymer with 1,6-hexanediamine and hexanedioic acid;	25776-72-1	51.00%	
				Fiber Glass Wool	65997-17-3	30.00%	
				Zinc oxide; Zinc white; C.I. pigment white 4	1314-13-2	0.50%	
				OP 935;Aluminum diethylphosphinate	225789-38-8	10.00%	
				zinc; boron; oxygen(-2) anion	12767-90-7	3.00%	
				Carbon Black	1333-86-4	0.50%	
				Other	-	5.00%	
Conn		Terminal Copper	0.016	Copper (metallic)	7440-50-8	92.33%	
				Tin	7440-31-5	7.00%	
				Other Element Phosphorus	INX-066	0.35%	
				Zinc	7440-66-6	0.20%	
				Iron;	7439-89-6	0.10%	
				Lead;	7439-92-1	0.02%	
Conn		Terminal Tin	0.001	Stannous methanesulfonate;Methanesulfonic acid tin(2+) salt	53408-94-9	45.00%	
				Methanesulfonic acid;Methylsulfonic acid	75-75-2	5.00%	
				Water;dihydrogen oxide	7732-18-5	50.00%	
Conn		Terminal Nickel	0.001	Sulfamic acid, nickel(2+) salt (2:1)	13770-89-3	50.00%	
				Water;dihydrogen oxide	7732-18-5	50.00%	
Conn		Terminal Gold	0.001	Potassium dicyanoaurate;Aurate(1-),bis(cyano-C)-, potassium	13967-50-5	100.00%	
Fuse-C	0.0152	Inner_Conductor	0.0001	Silver;	7440-22-4	100.00%	
Fuse-C		Marking	0.0001	Aluminum oxide;	1344-28-1	21.18%	
				Frits,chemicals;Bleihaltige Fritten, Chemikalien	65997-18-4	34.73%	
				manganese ferrite black spinel	68186-94-7	44.09%	
Fuse-C		Plating Tin	0.0003	Tin	7440-31-5	100.00%	
Fuse-C		Plating Nickel	0.0003	Nickel	7440-02-0	100.00%	
Fuse-C		Substrate	0.0129	Aluminum oxide;	1344-28-1	50.00%	
				Frits,chemicals;Bleihaltige Fritten, Chemikalien	65997-18-4	50.00%	
Fuse-C		Terminal	0.0015	Silver;	7440-22-4	93.40%	

				Frits,chemicals;Bleihaltige Fritten, Chemikalien	65997-18-4	6.60%	
Solder	5	Solder	5	Silver;	7440-22-4	2.70%	
				Tin	7440-31-5	85.00%	
				Copper (metallic)	7440-50-8	0.40%	
				Resin acids and resin acids, esters with glycerol;Resin acids and Rosin acids, esters with glycerol	8050-31-5	11.90%	
LB	1.22	Adhesive-1	0.114	2,4,6,8-Tetravinyl-2,4,6,8-tetramethylcyclotetrasiloxane;	2554-06-5	11.50%	
				Polysiloxane	-	38.50%	
				Cyclosiloxane	-	1.00%	
				Trisiloxane	-	11.00%	
				Silsesquioxane	-	37.00%	
				Silicone resin	-	1.00%	
LB		Adhesive-2	0.0221	Silicon dioxide	7631-86-9	15.00%	
				Polyacrylic acid	9003-01-4	80.00%	
				Triethylamine;N,N-diethylethanamine	121-44-8	4.00%	
				Aluminium hydroxide	21645-51-2	1.00%	
LB		Chip	0.0465	Indium Tin Oxide	50926-11-9	0.05%	
				Gallium; Liquid gallium; Ga	7440-55-3	4.65%	
				Indium;INE 07PB	7440-74-6	2.46%	
				Nitrogen;Diatomicnitrogen	7727-37-9	1.80%	
				Aluminum oxide;	1344-28-1	88.72%	
				Chromium	7440-47-3	0.0010%	
				Gold	7440-57-5	0.50%	
				Titanium	7440-32-6	0.02%	
				Platinum	7440-06-4	0.04%	
				Aluminium;	7429-90-5	0.01%	
				Silica, Crystalline	14808-60-7	0.84%	
				Titanium dioxide;	13463-67-7	0.91%	
LB		Coverlay	0.1549	Adhesive of epoxy resin	-	47.00%	
				Poly(pyromellitic dianhydride-co-4,4-oxydianiline)	25038-81-7	53.00%	
LB		Fccl	0.4499	Copper (metallic)	7440-50-8	80.00%	
				Poly(pyromellitic dianhydride-co-4,4-oxydianiline)	25038-81-7	20.00%	
LB		Gold_Plating	0.0059	Potassium dicyanoaurate;Aurate(1-),bis(cyano-C)-, potassium	13967-50-5	100.00%	
LB		Ink-1	0.0148	Formaldehyde polymer with (chloromethyl)oxirane and methylphenol, 4-cyclohexene-1,2-dicarboxylate 2-propenoate	182697-62-7	38.00%	
				4,4-propane-2,2-diylidiphenol - 2-(chloromethyl)oxirane (1:1)	25068-38-6	30.00%	
				Titanium dioxide;	13463-67-7	32.00%	
LB		Ink-2	0.0074	Epoxy Resin	-	36.40%	
				Silicon dioxide	7631-86-9	6.00%	
				Talc	14807-96-6	8.40%	
				Titanium oxide;Titanium dioxide	1317-80-2	26.30%	
				Dicyanodiamide;1-Cyanoguanidine	461-58-5	1.60%	
				Solvent naphtha	64742-94-5	3.00%	
				2-(2-Butoxyethoxy)ethyl acetate	124-17-4	2.70%	
				2-Butoxyethanol	111-76-2	9.30%	
				Leveling Agent and others	-	0.40%	
				Phenolic Resin	-	1.50%	
				Fumed silica	112945-52-5	0.90%	
				Amine Compound	-	3.50%	
LB		Molding_Material	0.1056	Polyester	-	64.00%	
				Titanium dioxide;	13463-67-7	18.000000%	
				Fiber Glass Wool	65997-17-3	18.00%	
LB		Nickel_Plating	0.0015	Nickel	7440-02-0	100.00%	
LB		Phosphor	0.0296	Aluminum cerium yttrium oxide	163584-80-3	100.00%	
LB		Pi_Stiffener	0.0811	Halogen-free&antimony-free of composite film glue	-	19.22%	
				Polyimide film	-	80.78%	
LB		Plating	0.0211	Silver;	7440-22-4	100.00%	
LB		Solder	0.06	Silver;	7440-22-4	0.26%	
				Tin	7440-31-5	86.04%	
				Copper (metallic)	7440-50-8	2.00%	
				Bismuth	7440-69-9	2.00%	
				溶劑	-	4.20%	
				松香	-	5.50%	
LB		Substrate	0.0845	Copper (metallic)	7440-50-8	97.53%	
				Iron;	7439-89-6	2.30%	
				Zinc	7440-66-6	0.10%	
				Other Element Phosphorus	INX-066	0.07%	
LB		Wire	0.0211	Gold	7440-57-5	99.99%	
				Trade secret	-	0.01%	
Housing	1	PC	1	Carbonic acid, diphenyl ester, polymer with 4,4-(1-methylethylidene)bisphenol	25929-04-8	99.00%	
				Other	INX-067	1.000000%	
				4,4-isopropylidenediphenol; bisphenol A;	80-05-7	0.002720%	
LGP	27.3	PC	1.3	Carbonic dichloride, polymer with 4,4-(1-methylethylidene)bis[phenol];	25971-63-5	99.90%	
				OTHER ADDITIVE	-	0.10%	

LGP		Protect_Film	26	Poly(ethylene)	9002-88-4	0.0001%	
				Poly(ethylene)	9002-88-4	100.00%	
Rear	115.29	Cover	114.73	Aluminium;	7429-90-5	92.55%	
				Magnesium	7439-95-4	5.70%	
				Manganese and its compounds	7439-96-5	1.40%	
				Chromium	7440-47-3	0.35%	
Rear		Mylar-1	0.12	Poly(ethylene terephthalate);PET	25038-59-9	50.00%	
				2-Propenoic acid, polymer with butyl 2-propenoate and ethenyl acetate;	25085-41-0	50.00%	
Rear		Mylar-2	0.12	2-Ethylhexyl acrylate	103-11-7	50.00%	
				Poly(ethylene terephthalate);PET	25038-59-9	50.00%	
Rear		Mylar-3	0.1	商業機密	-	3.00%	
				Silicon dioxide	7631-86-9	97.00%	
Rear		Ink	0.01	其他各種成分(如灰塵、雜質等)	-	2.00%	
				矽電劑-石墨烯	-	3.00%	
				環氧樹脂	-	25.00%	
				Carbon Black	1333-86-4	5.00%	
				2-Butanone;Ethyl methyl ketone	78-93-3	65.00%	
Rear		Rivet-1	0.1	Iron;	7439-89-6	98.23%	
				Manganese and its compounds	7439-96-5	1.28%	
				Silicon;	7440-21-3	0.0030%	
				Carbon;Activated carbon	7440-44-0	0.07%	
				Sulfur	7704-34-9	0.35%	
				Phosphorus	7723-14-0	0.07%	
Rear		Rivet-2	0.1	Sodium hypophosphite monohydrate;Sodium hypophosphite	10039-56-2	50.00%	
				Nickel(II) sulfate hexahydrate (1:1:6)	10101-97-0	50.00%	
Rear		Rivet-3	0.01	鉍沉淀物	-	0.0029%	
				水不溶物	-	0.0030%	
				氮含量	-	0.01%	
				氯化物	-	0.04%	
				Iron;	7439-89-6	0.0004%	
				Lead;	7439-92-1	0.0006%	
				Magnesium	7439-95-4	0.0019%	
				Manganese and its compounds	7439-96-5	0.0001%	
				Nickel	7440-02-0	99.93%	
				Cadmium	7440-43-9	0.0002%	
				Cobalt	7440-48-4	0.01%	
				Copper (metallic)	7440-50-8	0.0001%	
				Zinc	7440-66-6	0.0001%	
				Calcium;	7440-70-2	0.0004%	
Bezel	32.39	Ink	0.01	2-Butanone;Ethyl methyl ketone	78-93-3	50.00%	
				Phenolic Resin	9003-35-4	34.00%	
				Carbon Black	1333-86-4	10.00%	
				GLASSY CARBON;MWNT	308068-56-6	5.00%	
				Other	-	0.50%	
				H2O	-	0.50%	
Bezel		Substrate	32.22	Iron;	7439-89-6	98.80%	
				Carbon;Activated carbon	7440-44-0	0.20%	
				Manganese and its compounds	7439-96-5	0.40%	
				Aluminium;	7429-90-5	0.25%	
				Other Element Phosphorus	INX-066	0.05%	
				Sulfur	7704-34-9	0.05%	
				Zinc	7440-66-6	0.25%	
Bezel		Tape-1	0.01	Poly(ethylene terephthalate);PET	25038-59-9	14.60%	
				2-Propenoic acid, polymer with butyl 2-propenoate and ethenyl acetate;	25085-41-0	85.40%	
Bezel		Tape-2	0.15	SILICONE RUBBER;polydimethylsiloxanerubber	63394-02-5	96.00%	
				Silicone;Poly(dimethylsiloxane);Silicon	63148-62-9	0.40%	
				Silicon dioxide	7631-86-9	0.30%	
				Carbon Black	1333-86-4	0.30%	
				Bis(tert-butylidioxisopropyl)benzene;Bis[1-(tert-butylperoxy)-1-methylethyl]benzene	25155-25-3	2.00%	
				Poly(ethylene terephthalate);PET	25038-59-9	0.01	
Db_Adhesive	0.01	Adhesive	0.01	Poly(ethylene terephthalate);PET	25038-59-9	0.08	
				Butyl acrylate-methyl methacrylate polymers;Butyl acrylate-methyl methacrylate copolymer	25852-37-3	0.3	
				PIPERYLENE/BUTENE/PENTENE COPOLYMER;Distillates (petroleum), C3-6, piperylene-rich, polymers with isobutylene	152698-66-3	0.08	
				Cellulose microcrystalline; alpha-Cellulose	9004-34-6	0.54	
Conductive_Tape	0.029	Adhesive	0.029	Polyester Fabric	-	0.4	
				Nickel	7440-02-0	0.03	
				Copper (metallic)	7440-50-8	0.16	
				Hot Melt Resin; b-D-Glucopyranoside, (2E)-3-phenyl-2-propen-1-yl;b-D-Glucopyranoside, (2E)-3-phenyl-2-propenyl (9CI)	85026-55-7	0.41	
Isolation_Tape	5.28	Adhesive-1	2.11	Poly(ethylene terephthalate);PET	25038-59-9	0.4	

				2-Propenoic acid, polymer with butyl 2-propenoate and ethenyl acetate;	25085-41-0	0.6	
Isolation_Tape		Adhesive-2	1.06	Poly(ethylene terephthalate);PET	25038-59-9	0.6	
				2-Propenoic acid, polymer with butyl 2-propenoate and ethenyl acetate;	25085-41-0	0.4	
Isolation_Tape		Plastics	2.11	Carbon Black	1333-86-4	0.05	
				Poly(ethylene terephthalate);PET	25038-59-9	0.75	
				Phosphonic acid, P-methyl-, diphenyl ester, polymer with 4,4'-(1-methylethylidene)bis[phenol]	68664-06-2	0.2	
Fasten_Tape	0.18	Adhesive	0.13	prop-2-enoic acid - 2-ethylhexyl prop-2-enoate (1:1)	25134-51-4	0.7	
				Poly(ethylene terephthalate);PET	25038-59-9	0.3	
Fasten_Tape		Plastics	0.05	Poly(ethylene terephthalate);PET	25038-59-9	1	
Reflector_Tape	0.11	Adhesive-1	0.06	prop-2-enoic acid - 2-ethylhexyl prop-2-enoate (1:1)	25134-51-4	0.7	
				Poly(ethylene terephthalate);PET	25038-59-9	0.3	
Reflector_Tape		Adhesive-2	0.05	Poly(ethylene terephthalate);PET	25038-59-9	0.86	
				Titanium dioxide;	13463-67-7	0.14	
Masking_Tape	0.001	Adhesive	0.001	2-Propenoic acid,2-methyl-, methyl ester, homopolymer	9011-14-7	0.4	
				Poly(ethylene terephthalate);PET	25038-59-9	0.599831	
				Antimony	7440-36-0	0.000169	
Thermal_PAD	0.56	Adhesive	0.56	Acrylic acid	9063-87-0	0.3	
				Fiber Glass Wool	65997-17-3	0.1	
				Aluminum oxide;	1344-28-1	0.6	
Label	0.4	Adhesive	0.1	2-Propenoic acid, polymer with butyl 2-propenoate and ethyl 2-propenoate;	27322-15-2	0.5	
				prop-2-enoic acid - 2-ethylhexyl prop-2-enoate (1:1)	25134-51-4	0.31	
				Resin acids and Rosin acids, polymd., esters with pentaerythritol;Pentalyn K	65997-12-8	0.19	
Label		Ink	0.02	丙烯酸多元醇酯聚合物		0.22	
				Polyacrylic acid; 2-Propenoic acid homopolymer	9003-01-4	0.1	
				Poly[oxy(methyl-1,2-ethanediy)]-,a,a,a-1,2,3-propanetriyltris[w-[(1-oxo-2-propen-1-yl)oxy]-];Actilane 432	52408-84-1	0.26	
				2-Propenoic acid, 2-[[[2,2-bis[[[(1-oxo-2-propenyl)oxy]methyl]butoxy]methyl]-2-ethyl-1,3-propanediy];Aronix M 408	94108-97-1	0.1	
				1-Butanone,2-(dimethylamino)-2-[(4-methylphenyl)methyl]-1-[4-(4-morpholinyl)phenyl]-;Irgacure 379	119344-86-4	0.01	
				2,4-Diethyl-9H-thioxanthen-9-one	82799-44-8	0.03	
				4-Methylbenzophenone;Phenyl p-tolyl ketone	134-84-9	0.03	
				二乙基酮类衍生物		0.03	
				Carbon Black	1333-86-4	0.16	
				Carbonic acid,magnesium salt (1:1);Magnesiumcarbonate (6Cl,7Cl)	546-93-0	0.03	
				polyethylene; LMPE; LDPE; LLDPE; low density po	9002-88-4	0.03	
Label		Label	0.28	Poly(ethylene terephthalate);PET	25038-59-9	0.79	
				silica; silicon dioxide;	14464-46-1	0.21	